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Attorney Docket No.: 041993-5122

*MW 9-9-99*

To the Assistant Commissioner for Patents:  
Please record the attached original documents or copy thereof.

ATTN: BOX ASSIGNMENT

1. Name of conveying party(ies):

1. Bo-Seok OH

2. Name and address of receiving party(ies):

Name: Hyundai Micro Electronics Co., Ltd.

Internal Address:

Additional name(s) of conveying party(ies) attached?

Yes  No

Street Address: 1, Hyangjeong-Dong, Hungduk-Ku,  
Cheongju, Choongcheongbuk-Do, Korea

City:

State:

Zip:

Additional name(s) & address(es) attached?

Yes  No

3. Nature of conveyance:

Assignment  Merger  
 Security Agreement  Change of Name  
 Other \_\_\_\_\_

Execution Date: August 10, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application the execution date of the application is:  
August 10, 1999

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached:  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Robert J. Gaybrick

Internal Address: Morgan, Lewis & Bockius LLP  
Customer No. 09629

Street Address: 1800 M Street, N.W.  
City: Washington State: D.C. Zip: 20036

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R §3.41): \$40.00  
 Enclosed  
 Authorized to be charged to deposit account 50-0310

8. Deposit account number: 50-0310  
Attach duplicate of page if paying by deposit account

9. Statement and Signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

J. Michael Thesz  
Name of Person Signing

Signature

September 9, 1999  
Date

09/16/1999 DNGUYEN 00000212 09392632

Total number of pages including cover sheet, attachments and documents: 2

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## ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

## CAPACITOR FOR SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREOF

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Serial No. \_\_\_\_\_); and

WHEREAS, Hyundai Micro Electronics Co., Ltd., a corporation of Korea, whose post office address is 1, Hyangjeong-Dong, Hungduk-Ku, Cheongju, Choongcheongbuk-Do, Korea (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

<b>Full Name of Sole or First Assignor</b> Bo-Seok OH	Assignor's Signature <i>Oh boseok</i>	Date <i>8/10/99</i>
Address : LG Semiconductor boarding house 511, 1, Hyangjeong-Dong, Hungduk-Ku, Cheongju, Choongcheongbuk-Do, Korea		Citizenship Republic of Korea

Full Name of Second Assignor	Assignor's Signature	Date
Address		Citizenship

WA01A/182444.1

Names of additional inventors attached  Yes  No

**Morgan, Lewis & Bockius LLP**